

RELIABILITY REPORT
FOR
MAX1823BEUB+
PLASTIC ENCAPSULATED DEVICES

April 8, 2011

MAXIM INTEGRATED PRODUCTS

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Approved by
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Conclusion

The MAX1823BEUB+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX1823 is a dual, current-limited switch with autoreset specifically made for USB applications. The autoreset feature latches the switch off if the output is shorted, saving system power. The switch reactivates when the short circuit is removed. Each channel is guaranteed to supply 720mA and meet USB specifications. Low quiescent supply current (50 μ A) and standby current (3 μ A) conserve battery power in portable applications. The MAX1823 has multiple safety features to ensure that the USB port is protected. Built-in thermal-overload protection limits power dissipation and junction temperature. Accurate internal current-limiting circuitry protects the input supply against both overload and short-circuit conditions. Independent fault signals (active-low FAULTA and active-low FAULTB) notify the microprocessor (μ P) when a thermal-overload, current-limit, undervoltage-lockout (UVLO), or short-circuit fault occurs. A 20ms fault-blanking feature ignores momentary faults, such as those caused when hot swapping a capacitive load, preventing false alarms to the host system. The MAX1823A/MAX1823B also block reverse current (current from OUT_ to IN_) while in shutdown. The MAX1823 is available in a space-saving 10-pin μ MAX[®] package. The MAX1823/MAX1823A are enabled with an active-low signal, and the MAX1823B/MAX1823H are enabled with an active-high signal. For a single version of this device, refer to the MAX1946 data sheet. For a triple version, refer to the MAX1940 data sheet.

II. Manufacturing Information

A. Description/Function:	Dual USB Switch with Fault Blanking and Autoreset
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	October 24, 2003

III. Packaging Information

A. Package Type:	10-pin uMAX
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-0847
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	180°C/W
K. Single Layer Theta Jc:	42.0°C/W
L. Multi Layer Theta Ja:	113.1°C/W
M. Multi Layer Theta Jc:	42.0°C/W

IV. Die Information

A. Dimensions:	87 X 62 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 50 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 22.0 \times 10^{-9}$$

$$\lambda = 22.0 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot SOD1AQ001A D/C 0333)

The PN69-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-800V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

Table 1
Reliability Evaluation Test Results

MAX1823BEUB+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	50	0	SOD1AQ001A, D/C 0333

Note 1: Life Test Data may represent plastic DIP qualification lots.